1N5711

SMALL SIGNAL SCHOTTKY DIODE

DO-35

DESCRIPTION

Metal to silicon junction diode featuring high breakdown, low turn-on voltage and ultrafast switching. Primarly intended for high level UHF/VHF detection and pulse application with broad dynamic range. Matched batches are available on request

ABSOLUTE RATINGS (limiting values)

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Symbol	Parameter		Value	Unit	
V _{RRM}	Repetitive Peak Reverse Voltage		70	V	
l _F	Forward Continuous Current*	$T_a = 25^{\circ}C$	15	mA	
P _{tot}	Power Dissipation*	$T_a = 25^{\circ}C$	430	mW	
T _{stg} T _j	Storage and Junction Temperature Range		- 65 to 200 - 65 to 200	°C	
TL	Maximum Lead Temperature for Soldering during 10s at 4mm from Case		230	°C	

THERMAL RESISTANCE

	from Case			
			STSC.COM	
THERMAL	RESISTANCE	A GALL STATE WWW.V	1.4-	
Symbol	Test Conditions	Value	Unit	
R _{th(j-a)}	Junction-ambient*	400	°C/W	

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol		Test Conditions	Min.	Тур.	Max.	Unit
V _{BR}	$T_{amb} = 25^{\circ}C$	I _R = 10μA	70		-10	V
V _F * *	$T_{amb} = 25^{\circ}C$	I _F = 1mA		192	0.41	V
	$T_{amb} = 25^{\circ}C$	I _F = 15mA		AL 44	1	
I _R * *	$T_{amb} = 25^{\circ}C$	V _R = 50V			0.2	μA

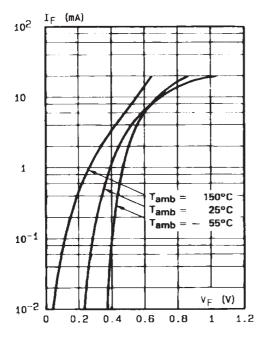
DYNAMIC CHARACTERISTICS

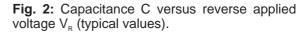
Symbol	AP CELE	Test Conditions			Тур.	Max.	Unit
С	$T_{amb} = 25^{\circ}C$	$V_R = 0V$	f = 1MHz			2	рF
τ	$T_{amb} = 25^{\circ}C$	$I_F = 5mA$	Krakauer Method			100	ps

* On infinite heatsink with 4mm lead length ** Pulse test: $t_p \le 300 \mu s \ \delta < 2\%$. Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.



Fig. 1: Forward current versus forward voltage at low level (typical values).





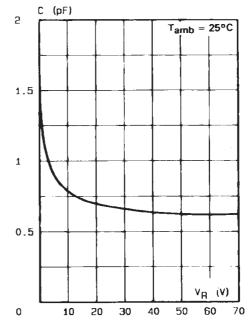


Fig. 3: Reverse current versus ambient temperature.

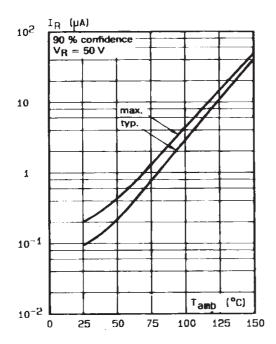
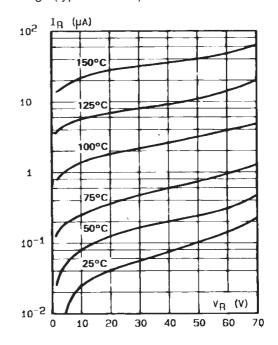


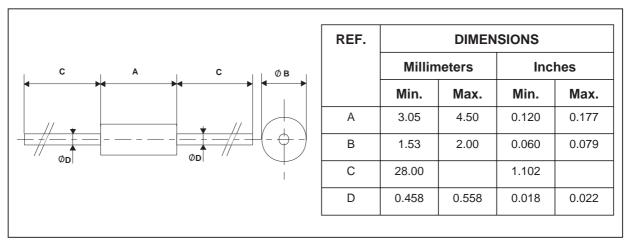
Fig. 4: Reverse current versus continuous reverse voltage (typical values).



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PACKAGE MECHANICAL DATA

DO-35



Cooling method : by convection and conduction Marking: clear, ring at cathode end. Weight: 0.15g

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